

The silver paste is formulated for screen printing application on the float glass, for the **fine line printing** specially (<0.40 mm width). It is produced with a very fine and conductive silver powder, that gives an excellent **low resistivity** and a dense, well sintered, fired film. It demonstrates excellent chemical resistance. It withstands the bleed through of the soldered “T-piece” adhesion.

PROCESSING CONDITIONS

Printing: 180 – 220 mesh screen and 0.30 mm minimum line width are recommended.

Soldering: 47% Sn, 40% Pb, 10% Bi, 3% Ag solder at 230°C.

Shelf life: 8 months @ 4°C-10°C, 6 months @ 10-24°C

Thinners: Thinning is not recommended, the paste is optimized to the correct viscosity for screen printing. Use the Chimet 0202 IT/0201IT to replace solvent losses, by contacting the local Chimet technician

TYPICAL PROPERTIES

Metal content:

Ag **80.0 %**

Sheet Resistance:

12 µm fired film thickness **2.0 mΩ/□**

Resistivity:

2.4 µΩ · cm

Viscosity:

10 r.p.m. **50 – 60 Pa.s**

STANDARD TEST CONDITIONS

Viscosity test:

Viscosimeter Brookfield DV II, Cylinder $\varnothing = 4$ cm h =7 cm , Spindle 7 R at 10 r.p.m. and 23.5 ($\pm 0,5$)°C.

Resistance test:

Circuit: 1000 x 1 mm
Printing : 250 mesh
Drying : 120°C, 10 minutes
Firing: flash firing @ 740°C, 4 minutes
Fired thickness: Taylor-Hobson profilometer

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